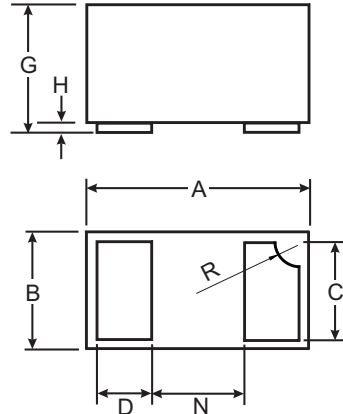


### Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

- Case: DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Dot
- Terminals: Finish - NiPdAu annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking: L1, Dot Denotes Cathode Side
- Ordering Information: See Page 2
- Weight: 0.001 grams



DFN1006-2			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	0.47	0.53	0.50
H	0	0.05	0.03
N	—	—	0.40
R	0.05	0.15	0.10
All Dimensions in mm			

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RRWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
Forward Continuous Current	I <sub>F</sub>	200	mA
Repetitive Peak Forward Current	I <sub>FRM</sub>	300	mA
Forward Surge Current	I <sub>FSM</sub>	600	mA
@ t < 1.0s			

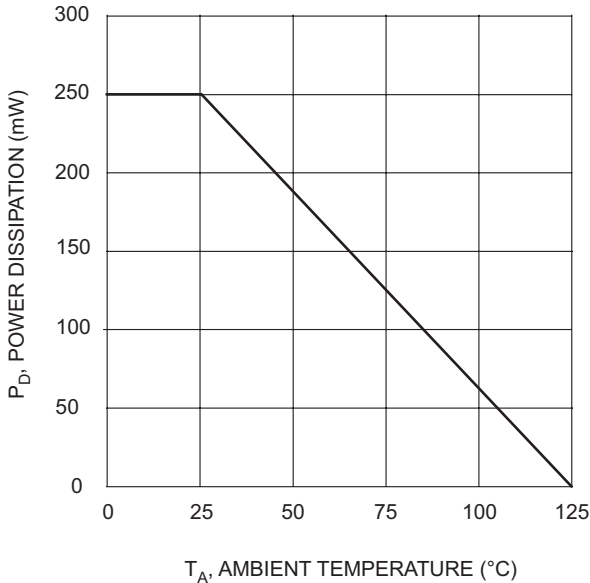
### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P <sub>d</sub>	250	mW
Thermal Resistance, Junction to Ambient Air (Note 4)	R <sub>θJA</sub>	400	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +125	°C

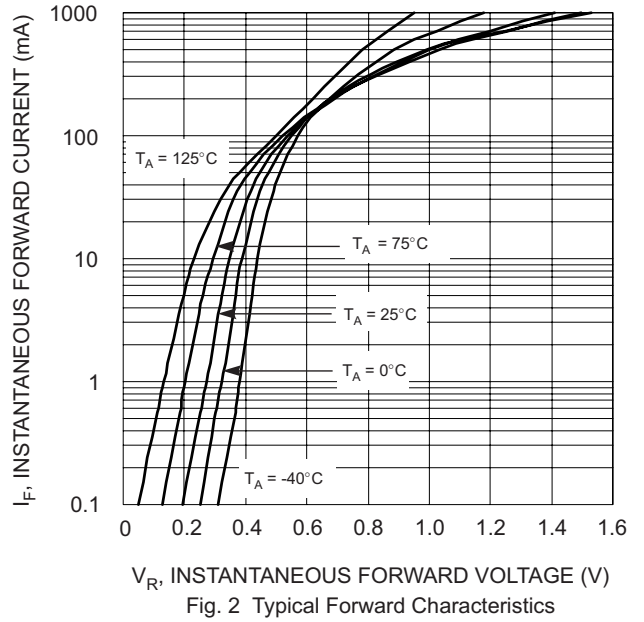
### Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	—	240 320 400 500 1000	mV	I <sub>F</sub> = 0.1mA I <sub>F</sub> = 1mA I <sub>F</sub> = 10mA I <sub>F</sub> = 30mA I <sub>F</sub> = 100mA
Reverse Leakage Current (Note 3)	I <sub>R</sub>	—	—	2.0	μA	V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	—	—	10	pF	V <sub>R</sub> = 1.0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	—	5.0	ns	I <sub>F</sub> = 10mA through I <sub>R</sub> = 10mA to I <sub>R</sub> = 1.0mA, R <sub>L</sub> = 100Ω

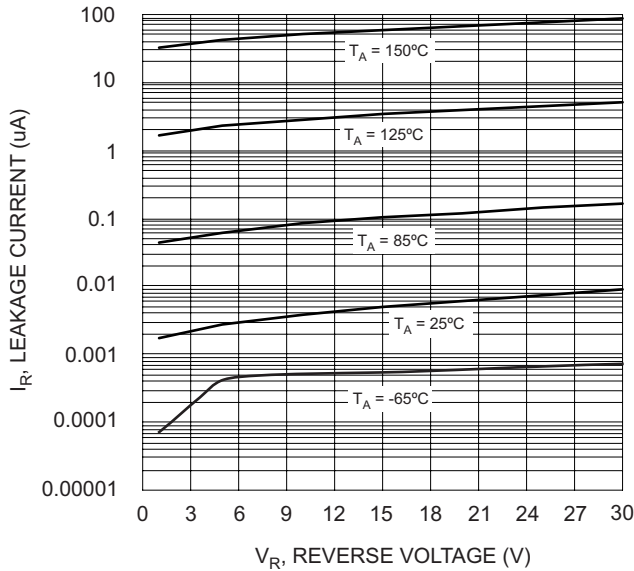
- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Short duration pulse test used to minimize self-heating effect.
  4. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>. T<sub>A</sub> = 25°C.



$T_A$ , AMBIENT TEMPERATURE (°C)  
Fig. 1 Power Derating Curve



$V_R$ , INSTANTANEOUS FORWARD VOLTAGE (V)  
Fig. 2 Typical Forward Characteristics



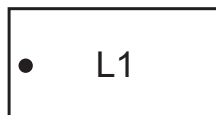
$V_R$ , REVERSE VOLTAGE (V)  
Fig. 3 Typical Reverse Characteristics

**Ordering Information** (Note 4)

Device	Packaging	Shipping
BAT54LP-7	DFN1006-2	3000/Tape & Reel

Notes: 4. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



L1 = Product Type Marking Code, Dot Denotes Cathode Side

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